



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

18-FEB-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13312

TITLE: Initial PCN for Qualification of VHVIC 8 Lead PDIP Products at AIT

EFFECTIVE DATE: 18-JUN-2004

AFFECTED CHANGE CATEGORY: Subcontractor Assembly Site

AFFECTED PRODUCT DIVISION: Analog Products

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Representative or Jack Cartwright <RWL070@onsemi.com>

NOTIFICATION TYPE:
Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is a Initial Product Change Notice to make customers aware that Advanced Interconnect Technology (AIT), located in Batam, Indonesia is being qualified as a supplemental manufacturing source for ON Semiconductor's VHVIC 8 lead PDIP products. AIT is QS9000 and ISO9002 certified, and has been a qualified subcontractor for ON Semiconductor devices since 1990. AIT is the primary supplier to ON Semiconductor for Analog 8/14/16 lead PDIP and VHVIC 16 lead PDIP products. The VHVIC 8 lead PDIP package will be qualified to run specific devices that are currently processed at ASE's Penang, Malaysia location. This is not a transfer but a capacity expansion.

Device parameters will continue to meet all Data Book specifications, and reliability will continue to meet or exceed ON Semiconductor standards.



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QUALIFICATION PLAN:

RELIABILITY Plan: Package = 8 Lead PDIP, Devices = MC44608P40, NCP1200P60

Test	Conditions	Interval	SS
A/clave	Ta = 121 deg C, P =15 psig,RH = 100%	6hrs	2x80,80
HAST	Ta = 130 deg C,P =18.8 psig,RH = 85%	96hrs	2x80,80
UHAST	Ta = 130 deg C, P =18.8 psig,RH = 85%	96hrs	2x80,80
Temp Cycle	Ta = -65 to +150 deg C,	500cyc	2x80,80
BPS Bond Pull Strength			3x10
BS Bond Shear Test			3x10
DSS Die Shear Strength			3x10

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

- MC33260P
- MC44608P100
- MC44608P40
- MC44608P75
- NCP1000P
- NCP1001P
- NCP1002P
- NCP1010AP065
- NCP1010AP100
- NCP1010AP130
- NCP1011AP065
- NCP1011AP100
- NCP1011AP130
- NCP1012AP065
- NCP1012AP100
- NCP1012AP133
- NCP1013AP065
- NCP1013AP100
- NCP1013AP133
- NCP1014AP065
- NCP1014AP100
- NCP1050P100
- NCP1050P136
- NCP1050P44
- NCP1051P100
- NCP1051P136
- NCP1051P44
- NCP1052P100
- NCP1052P136
- NCP1052P44
- NCP1053P100
- NCP1053P136
- NCP1053P44
- NCP1054P100
- NCP1054P136
- NCP1054P44
- NCP1055P100
- NCP1055P136



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NCP1055P44
NCP1200AP100
NCP1200AP100G
NCP1200AP40
NCP1200AP40G
NCP1200AP60
NCP1200P100
NCP1200P100G
NCP1200P40
NCP1200P40G
NCP1200P60
NCP1200P60G
NCP1201P100
NCP1201P60
NCP1203P100
NCP1203P40
NCP1203P60
NCP1205P
NCP1205PG
NCP1207P
NCP1212P
NCP1216P100
NCP1216P133
NCP1216P65
NCP1217P100
NCP1217P133
NCP1217P65
NCP1230AP100
NCP1230AP133
NCP1230AP65
NCP1230P100
NCP1230P133
NCP1230P65
NCP1231P100
NCP1231P133
NCP1231P65
NCP1377BP
NCP1377P
NCP1378P
NCP1390P
NCP1601P
NCP1653P